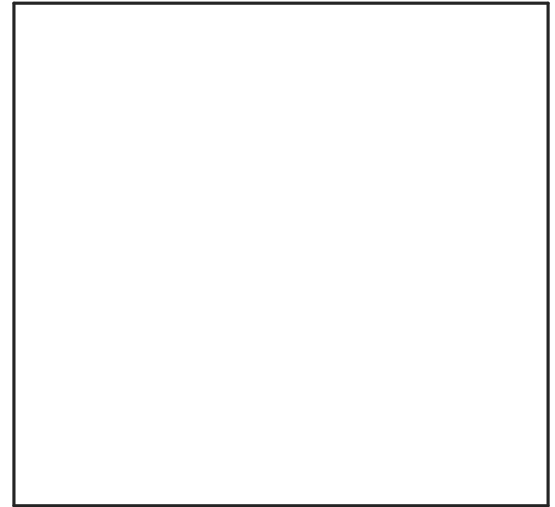


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30373	REV: B	SUN REV: Not In VersionControl
	TID #: .TID		
PLOT NAME = Top Assembly Drawing	GENERATED : 10/18/2017 17:14:10		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30373	REV: B	SUN REV: Not In VersionControl
	TID #: .TID		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/18/2017 17:14:11		TEXAS INSTRUMENTS

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